

Wire Solder - Preferred Fluxes

7	Key Features
268	 Low occurrence of solder ball spatter Conforms to IEC, JPCA and IPC halogen-free requirements with no intentionally added halogens and halides Low smoke and odor, clear residue for excellent joint aesthetics Excellent surface wettability and spreading suitable for robotic soldering and manual soldering Excellent manufacturing consistency and uniform quality, minimizes defects for all types of soldering Classified as ROL0 per J-STD-004B
275	 Colorless translucent residues Excellent solderability and fast wetting to a variety of surface finishes Low smoke and odor, low spattering Compatible with lead-free and leaded alloys Classified as ROL0 per J-STD-004 Compliant to Bellcore GR-78
245	 Highly reliable post-soldering residue Minimal residue Compatible with leaded and lead-free alloys Classified as ROL0 per J-STD-004 Compliant to Bellcore GR-78
48	 Unparalleled wetting performance Excellent solderability and fast wetting to a variety of surface finishes Eliminates the need and expense of cleaning Low spattering Low smoke and odor Classified as ROM1 per J-STD-004
44	 High activity RA formulation Passes both 85°C/85% RH and 40°C/90% RH IPC SIR testing Excellent solderability to a wide range of metalizations Industry standard RA cored wire for decades Classified as ROM1 per J-STD-004